To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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HAF2017(L), HAF2017(S)

Silicon N Channel Power MOS FET
Power Switching

REJ03G0234-0200Z
(Previous ADE-208-1637 (Z))
Rev.2.00
Apr.13.2004

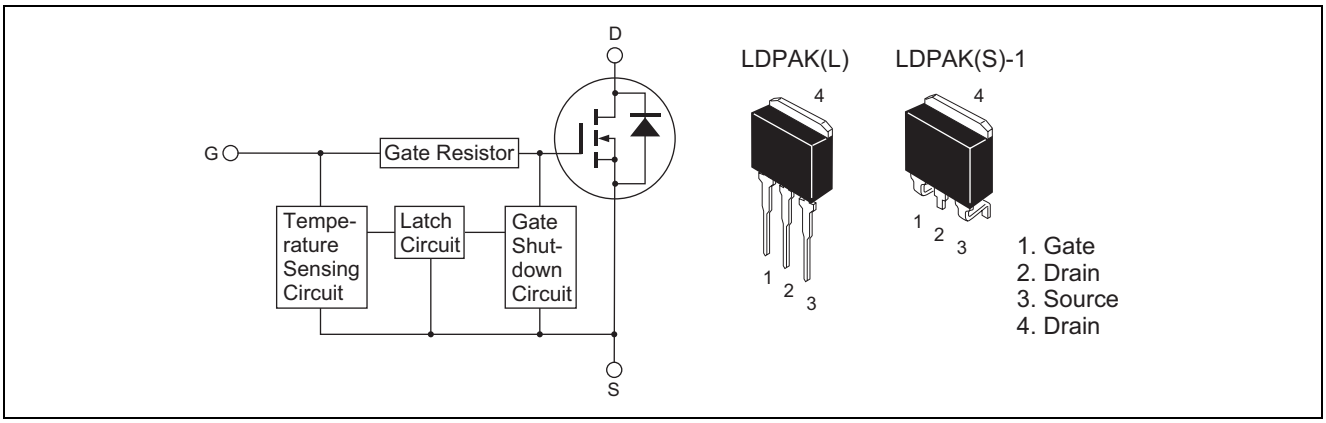
Descriptions

This FET has the over temperature shutdown capability sensing the junction temperature. This FET has the built-in over temperature shutdown circuit in the gate area. And this circuit operation to shutdown the gate voltage in case of high junction temperature like applying over power consumption, over current etc..

Features

- Logic level operation (4 to 6 V Gate drive)
- High endurance capability against to the short circuit
- Built-in the over temperature shutdown circuit
- Latch type shutdown operation (Need 0 voltage recovery)

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Rating	Unit
Drain to source voltage	V_{DSS}	60	V
Gate to source voltage	V_{GSS}	16	V
Gate to source voltage	V_{GSS}	–2.5	V
Drain current	I_D	20	A
Drain peak current	I_D (pulse) Note1	40	A
Body-drain diode reverse drain current	I_{DR}	20	A
Channel dissipation	Pch Note2	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

Notes: 1. PW ≤ 10µs, duty cycle ≤ 1%
2. Value at Tch = 25°C

Typical Operation Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage	V_{IH}	3.5	—	—	V	
Input voltage	V_{IL}	—	—	1.2	V	
Input current (Gate non shut down)	I_{IH1}	—	—	100	µA	Vi = 8V, V_{DS} =0
Input current (Gate non shut down)	I_{IH2}	—	—	50	µA	Vi = 3.5V, V_{DS} =0
Input current (Gate non shut down)	I_{IL}	—	—	1	µA	Vi = 1.2V, V_{DS} =0
Input current (Gate shut down)	$I_{IH(sd)1}$	—	0.8	—	mA	Vi = 8V, V_{DS} =0
Input current (Gate shut down)	$I_{IH(sd)2}$	—	0.35	—	mA	Vi = 3.5V, V_{DS} =0
Shutdown temperature	Tsd	—	175	—	°C	Channel temperature
Gate operation voltage	V_{OP}	3.5	—	12	V	

Electrical Characteristics

(Ta = 25°C)

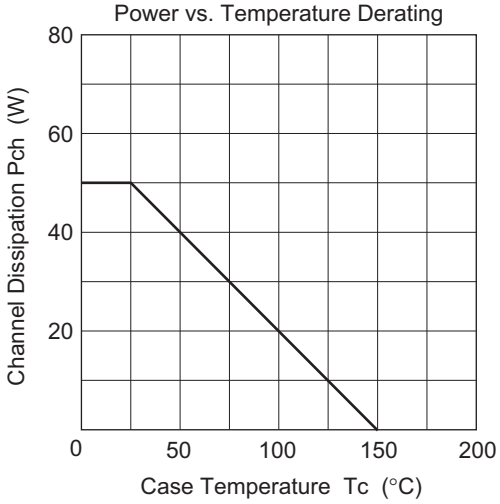
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Darin current	I_{D1}	1	—	—	A	V_{GS} = 3.5 V, V_{DS} = 2 V
Darin current	I_{D2}	—	—	10	mA	V_{GS} = 1.2 V, V_{DS} = 2 V
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	I_D = 10 mA, V_{GS} =0
Gate to source breakdown voltage	$V_{(BR)GSS}$	16	—	—	V	I_G = 800 µA, V_{DS} =0
	$V_{(BR)GSS}$	–2.5	—	—	V	I_G = –100 µA, V_{DS} =0
Gate to source leak current	I_{GSS1}	—	—	100	µA	V_{GS} = 8 V, V_{DS} =0
	I_{GSS2}	—	—	50	µA	V_{GS} = 3.5 V, V_{DS} =0
	I_{GSS3}	—	—	1	µA	V_{GS} = 1.2 V, V_{DS} =0
	I_{GSS4}	—	—	–100	µA	V_{GS} = –2.4 V, V_{DS} =0
Input current (shut down)	$I_{GS(OP)1}$	—	0.8	—	mA	V_{GS} = 8 V, V_{DS} =0
	$I_{GS(OP)2}$	—	0.35	—	mA	V_{GS} = 3.5 V, V_{DS} =0
Zero gate voltage drain current	I_{DSS}	—	—	10	µA	V_{DS} = 60 V, V_{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	1.4	—	2.6	V	V_{DS} = 10 V, I_D = 1 mA
Forward transfer admittance	$\|y_{fs}\|$	6	21	—	S	I_D =10 A, V_{DS} =10 V[Note3]
Static drain to source on state resistance	$R_{DS(on)}$	—	35	53	mΩ	I_D = 10 A, V_{GS} = 4.5 V[Note3]
	$R_{DS(on)}$	—	27	43	mΩ	I_D = 10 A, V_{GS} = 10 V[Note3]
Output capacitance	Coss	—	460	—	pF	V_{DS} = 10 V, V_{GS} =0, f = 1 MHz
Turn-on delay time	td(on)	—	8.7	—	µs	V_{GS} = 5 V, I_D= 10 A, R_L = 3 Ω
Rise time	tr	—	44.6	—	µs	
Turn-off delay time	td(off)	—	2	—	µs	
Fall time	tf	—	2.6	—	µs	
Body-drain diode forward voltage	V_{DF}	—	0.9	—	V	I_F = 20A, V_{GS} = 0
Body-drain diode reverse recovery time	trr	—	120	—	ns	I_F = 20 A, V_{GS} = 0, diF/dt = 50 A/µs
Over load shut down operation time[Note4]	t_{os1}	—	0.97	—	ms	V_{GS} = 5 V, V_{DD} = 16 V
	t_{os2}	—	0.57	—	ms	V_{GS} = 5 V, V_{DD} = 24 V

Notes: 3. Pulse test

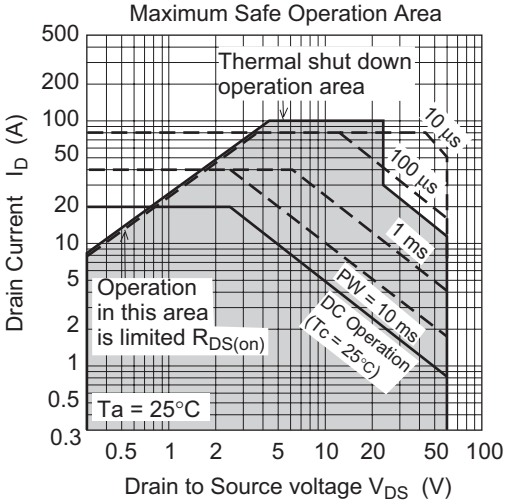
4. Include the time shift based on increasing of channel temperature when operate under over load condition.

Main Characteristics

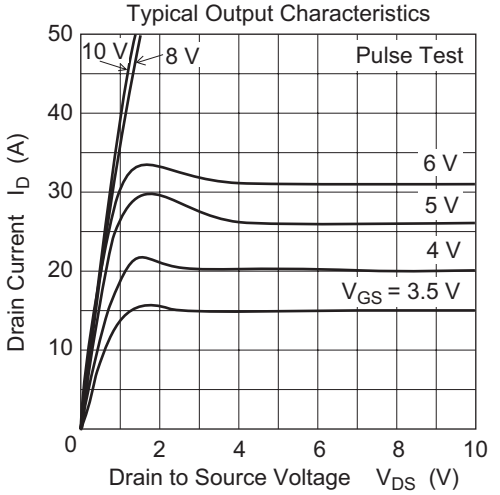
Power vs. Temperature Derating



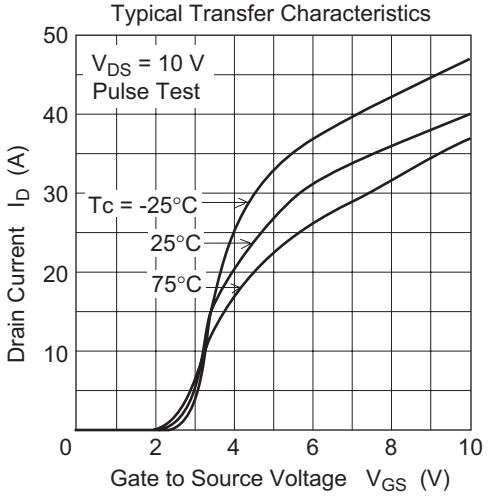
Maximum Safe Operation Area



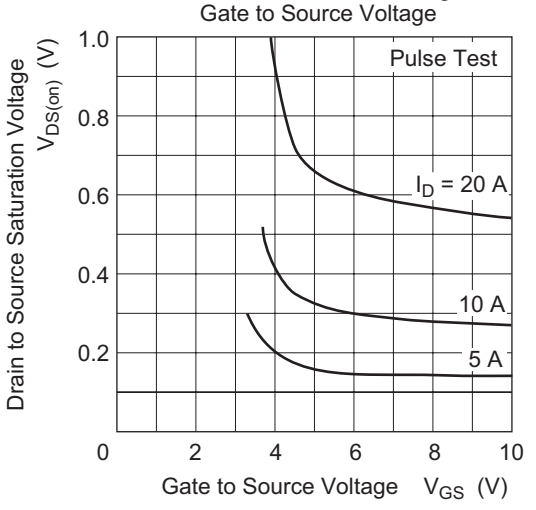
Typical Output Characteristics



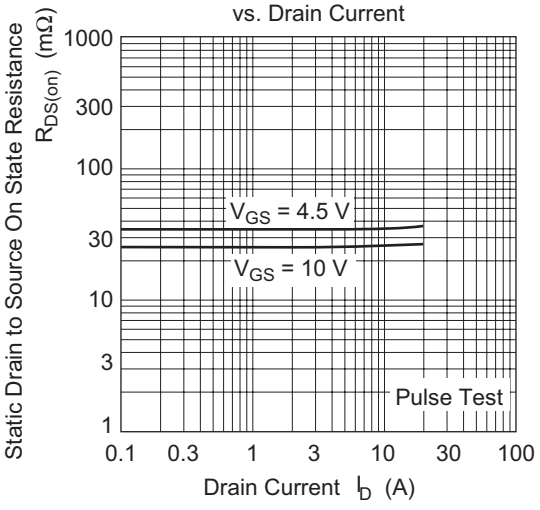
Typical Transfer Characteristics



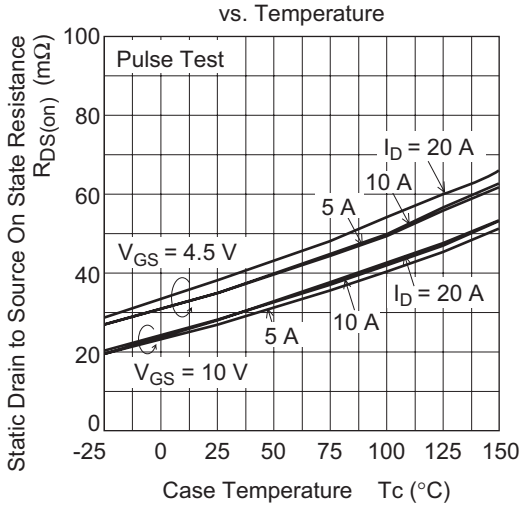
Drain Source Saturation Voltage vs. Gate to Source Voltage



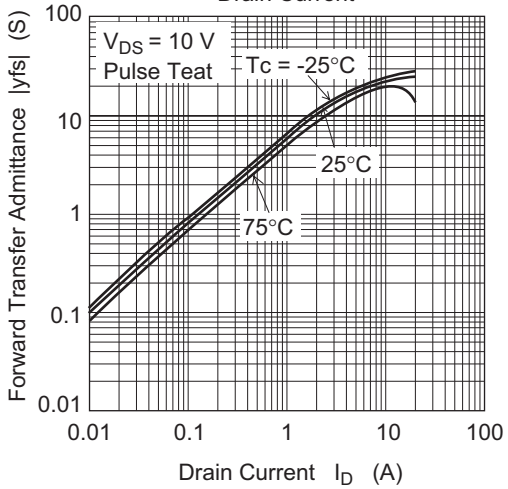
Static Drain to Source State Resistance vs. Drain Current



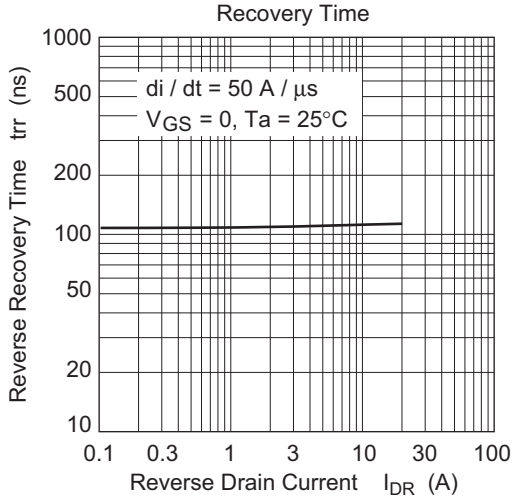
Static Drain to Source on State Resistance vs. Temperature



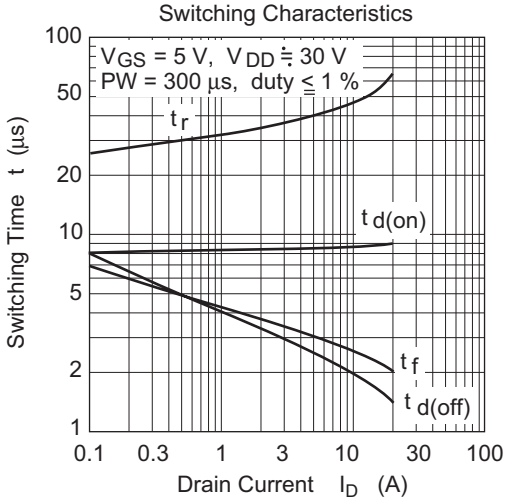
Forward Transfer Admittance vs. Drain Current



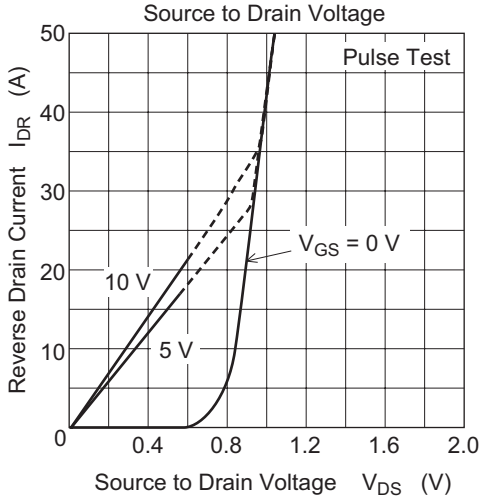
Body-Drain Diode Reverse Recovery Time



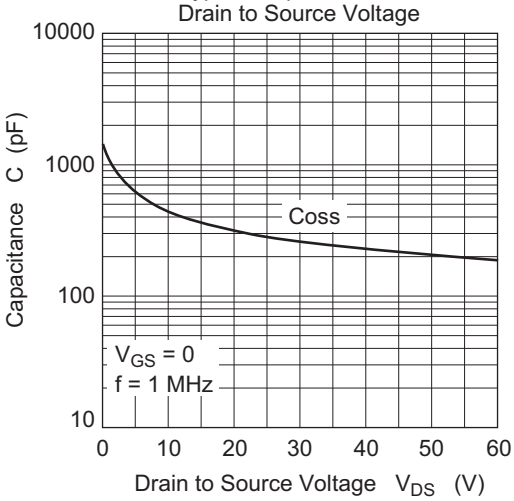
Switching Characteristics



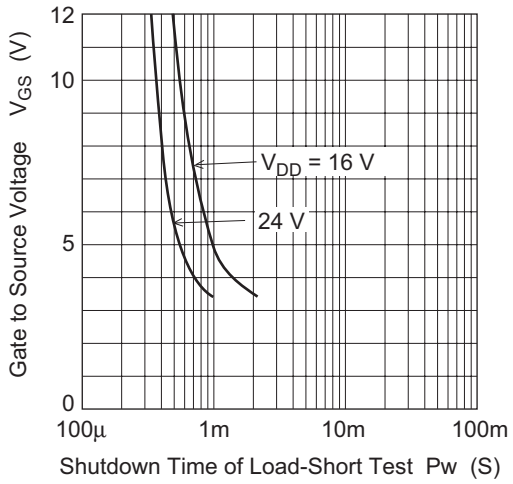
Reverse Drain Current vs. Source to Drain Voltage



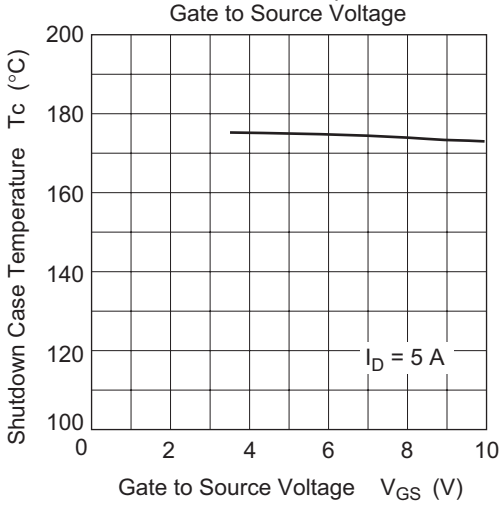
Typical Capacitance vs. Drain to Source Voltage



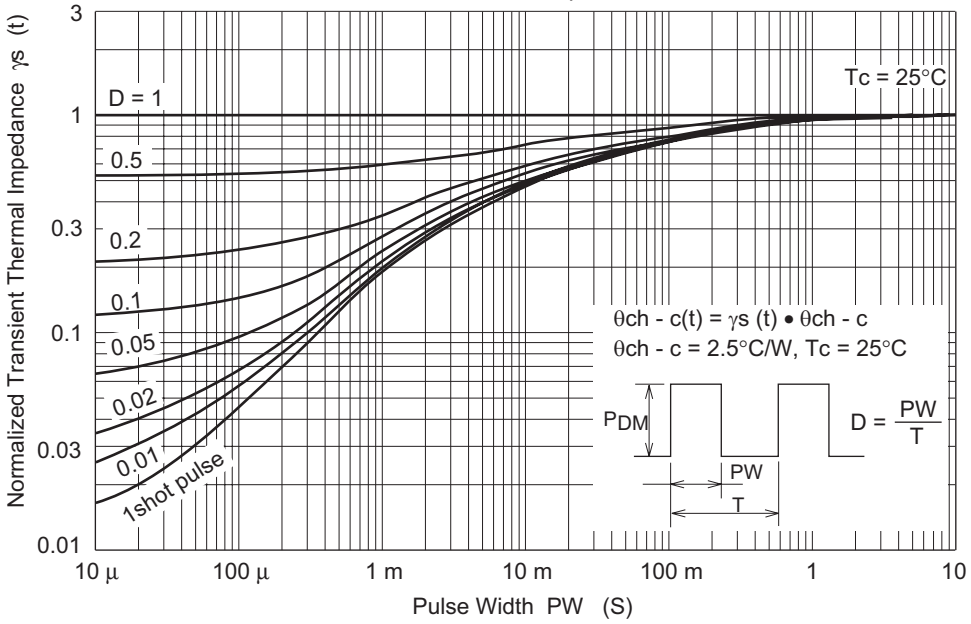
Gate to Source Voltage vs.
Shutdown Time of Load-Short Test



Shutdown Case Temperature vs.
Gate to Source Voltage

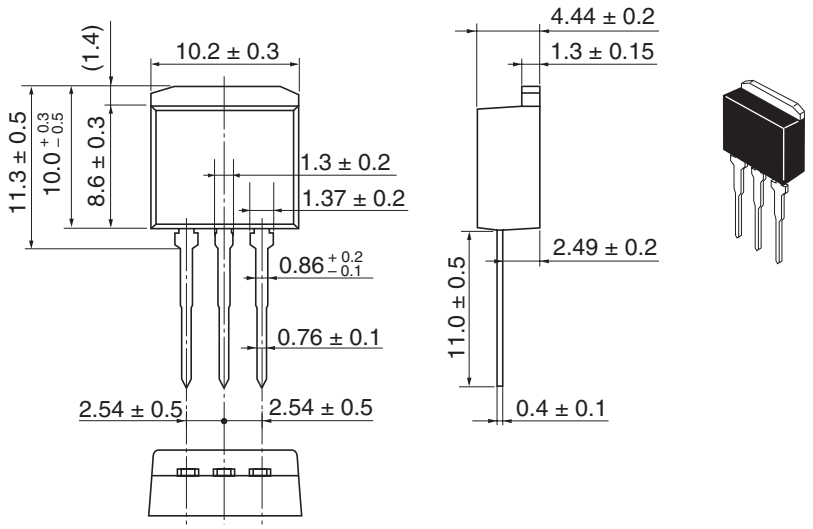


Normalized Transient Thermal Impedance vs. Pulse Width



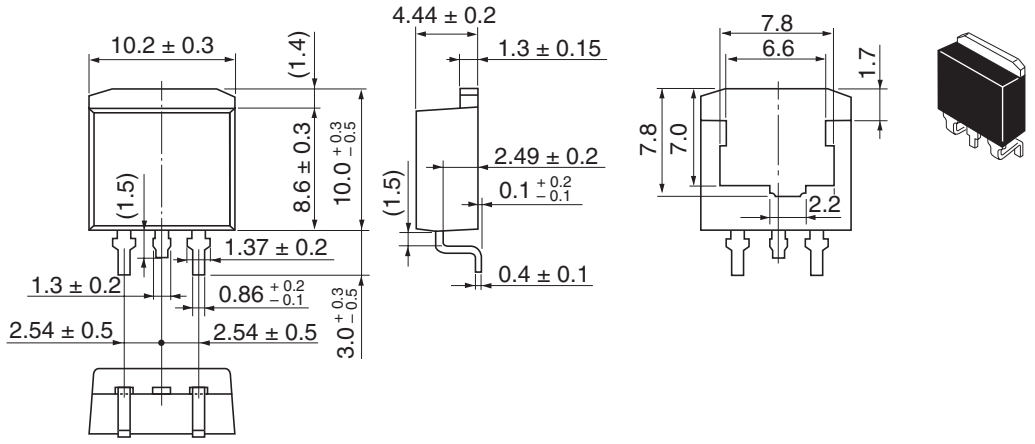
Package Dimensions

As of January, 2003
Unit: mm



Package Code	LDPAK (L)
JEDEC	—
JEITA	—
Mass (reference value)	1.40 g

As of January, 2003
Unit: mm



Package Code	LDPAK (S)-(1)
JEDEC	—
JEITA	—
Mass (reference value)	1.30 g

Ordering Information

Part Name	Quantity	Shipping Container
HAF2017-90L	Max: 50 pcs/ sack	Sack
HAF2017-90S	Max: 50 pcs/ sack	Sack
HAF2017-90STL	1000 pcs/ Reel	Embossed tape
HAF2017-90STR	1000 pcs/ Reel	Embossed tape

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